IN THE SPECIFICATION:

Please replace paragraph number **[0001]** with the following replacement paragraph:

[0001] This application is a continuation of application Serial No. 09/825,262, filed April 3, 2001, now U.S. Patent 6,461,690, issued October 8, 2002, which is a continuation of application Serial No. 09/625,938, filed July 26, 2000, now U.S. Patent 6,217,949, issued April 17, 2001, which is a continuation of application Serial No. 09/358,178, filed July 20, 1999, now U.S. Patent 6,113,992, issued September 5, 2000, which is a continuation of application Serial No. 08/944,684, filed September 30, 1997, now U.S. Patent 5,985,377, issued November 16, 1999, which is a continuation of application Serial No. 08/584,246, filed January 11, 1996, abandoned.

Please replace paragraph number **[0014]** with the following replacement paragraph:

[0014] In a more particular aspect of the invention, a stream of atomized particles of ~~B-stage~~B-stage epoxy with an added pigment of a desired color (white for example) is directed at the surface where the laser is actively marking the specimen. The epoxy reacts to the heat of the laser and cures to a visible white image coincident with the path of the laser. The excess particles, those which have not been directly irradiated by the laser beam, may be removed along with other debris from the work area by a debris removal system.

Please replace paragraph number **[0042]** with the following replacement paragraph:

[0042] Referring now to FIG. 7, a close-up view of the laser 28 in relation to the chip 12 is shown. The laser 28 projects a movable laser beam 52 onto the surface 54 of the chip 12 to mark the chip 12. As the laser beam 52 is directed toward the chip surface 54, a laser reactive marking material 58 is injected through an applicator or nozzle 60 onto the chip surface 54 at the same location 56 that the beam contacts the chip 12. The heat from the laser beam 52 fuses the laser reactive marking material 58 onto the chip surface 54. Laser reactive marking material 58 present on any non-irradiated portion of the chip 12 that has not been exposed to the laser beam 52 and ~~is therefore unreacted~~is, therefore, unreacted, does not bond to the chip surface 54 and is subsequently removed.

Please replace paragraph number **[0045]** with the following replacement paragraph:

[0045] In FIG. 8, an alternate embodiment is shown having a ribbon dispenser 66 comprised of a feed reel 68 and a take-up reel 70. The ribbon dispenser 66 dispenses a ribbon or strip of ink bearing ~~material~~ribbon 72 from the feed reel 68 to the take-up reel 70. The ribbon 72 extends over and is proximate to the surface 54 of the chip 12. The ribbon 72 may also extend over a number of chips 12 or several ribbon dispensers 66 may be placed side by side so that marking of several chips 12 can occur sequentially or so that multiple colors may be used in the marking process. The chips 12 are allowed to pass under the ribbon 72 as they slide along the track 14. When the chips have moved to the marking area 25, the laser 28 projects a laser beam 52 onto the surface of the ribbon 72 and transfers ink from the ribbon 72 onto the surface 54 of the chip 12. One advantage of the embodiment of FIG. 8 is the elimination of liquid pigments and coolants, the latter being due to absorbance of the laser energy by the ribbon 72 carrying the marking material. Another advantage is that the marking process using a ribbon 72 is cleaner in that no excess particles of marking material are present in the marking area to contaminate the marking area and chip in undesired areas.